These 3 one-hour webinars can be taken in total or separately, but to gain the most benefit it is recommended to attend the whole series in order. A brief description of each session follows:

**Session One: Overview of Polymers used in Electronic Packaging**
This session will provide a broad overview of polymers and the important structure-property-process-performance relationships for electronic packaging. Topics to be covered:
- Thermosetting polymers versus thermoplastics
- Temperature dependence of physical properties
- Thermosetting polymers; curing, curing mechanisms (heat and light cured), network formation
- Overview of key chemistries used (epoxies, acrylates, polyimides, bismaleimides, curing agents, and catalysts)

**Session Two: Polymer-based Materials for Semiconductor Packaging**
This session will build on the previous webinar and go into more details for specific applications. We will cover in more depth the chemistries, material properties, and process considerations for:
- Adhesives (both paste and film)
- Capillary Underfills
- Packaging Substrate Materials
- Encapsulants (mold compounds) and coatings

**Session Three: Rheological and Adhesion Requirements for Polymers used in Semiconductor Packaging**
This session will provide an introduction to two critical areas governing the performance of polymer-based materials used in packaging semiconductors. In most cases, adhesives, underfills, mold compounds and coatings are applied as a viscous liquid and then cured. The flow properties of these materials are critical to performance in high volume manufacturing. Additionally, the adhesive properties are critical for long-term reliability performance. This session will cover the basics in:
- Introduction to the rheological properties of adhesives (shear thinning, viscosity, time dependence, rheology changes during curing)
- Introduction to rheological characterization methods (various types of rheometers, and basic techniques)
- Introduction to Adhesion Science
- Polymer chemistries of typical adhesives, bonding mechanisms

Contact Jeff to discuss how he can help increase the impact of your next event by developing a tailored presentation to captivate your audience.
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